Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1-5. (Cancelled)

6. (Currently amended) A recycling method for recycling waste particles, ~~as a material to be melted or mixed, a cake that is obtained by~~ comprising:

~~solidifying particle generated at a step of~~ machining a crystal ingot into a wafer[,] or ~~at a step of~~ machining a semiconductor wafer;

solidifying into a cake, particles generated by machining the crystal ingot or the semiconductor wafer; and

melting the cake.

7. (Currently amended) A recycling method for recycling waste particles ~~employing as a material to be melted, a cake that is obtained by solidifying particle generated at a step of~~ comprising:

machining a crystal ingot into a wafer[,] or ~~at a step of~~ machining a semiconductor wafer;

solidifying into a cake, particles generated by machining the crystal ingot or the semiconductor wafer; and ~~for~~

recycling said cake as an ingot.

8. (Currently amended) A recycling method for recycling waste particles ~~employing as a material to be melted, a cake that is obtained by solidifying, at a predetermined water content, particles generated at a step of~~ comprising:

machining a crystal ingot into a wafer[,] or ~~at a step of~~ machining a semiconductor wafer;[,]

solidifying into a cake at a predetermined water content, particles generated by machining the crystal ingot or the semiconductor wafer; and ~~for~~

melting said cake ~~recycling~~ to recycle said cake as an ingot.

9. (Currently amended) A method for fabricating a semiconductor ingot ~~wherein a cake that is obtained by solidifying, at a predetermined water content and without a reaction with a chemical occurring, particles generated at a step of~~ comprising:

machining a crystal ingot into a wafer[,] or ~~at a step of~~ machining a semiconductor wafer; ~~, is employed as a material to be molted~~

solidifying into a cake at a predetermined water content and without any chemical reactions, particles generated by machining the crystal ingot or the semiconductor wafer; and

melting said cake.

10. (Currently amended) A recycling method according to one of claims 6 to 8, wherein ~~said~~ machining ~~step is an~~ comprises abrading, grinding or polishing, dicing, back grinding or wafer polishing ~~step~~.

11. (Currently amended) A method according to claim 9, wherein ~~said~~ machining ~~step is an~~ comprises abrading, grinding or polishing, dicing, back grinding or wafer polishing ~~step~~.

12- 18. (Cancelled)

19. (New) A method for processing particles comprising:

solidifying into a cake, particles that are generated by machining a crystal ingot into a wafer or machining a semiconductor wafer; and

melting the cake into an ingot.

20. (New) A method according to claim 19, further comprising:

solidifying said particles at a predetermined water content, without any chemical reactions.

21. (New) A method according to claim 19, wherein machining comprises abrading, grinding or polishing.

22. (New) A method according to claim 19, wherein machining said semiconductor wafer comprises dicing, back grinding or wafer polishing.

23. (New) A method according to claim 19, wherein said particles comprises Si flakes.

24. (New) A recycling method for recycling waste particles, comprising:

melting a cake which is produced by solidifying particles generated by machining a crystal ingot into a wafer or machining a semiconductor wafer.

25. (New) A recycling method for recycling waste particles comprising:

melting a cake to recycle the cake as an ingot, said cake produced by solidifying particles generated by machining a crystal ingot or a semiconductor wafer at a predetermined water content.

26. (New) A method for fabricating a semiconductor ingot comprising:

melting a cake which is produced by solidifying particles generated by machining a crystal ingot or a semiconductor wafer at a predetermined water content and without any chemical reactions.

27. (New) A method for processing particles comprising:

melting a cake into an ingot, said cake produced by solidifying particles that are generated by machining a crystal ingot into a wafer or machining a semiconductor wafer.